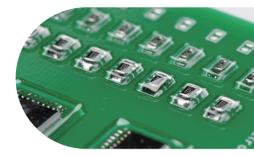


Digital Packaging Technology For PCBA

Pixel Level Whole Area Processing Technology for PCBA

2D single-layer image printing | 3D multi-layer three-dimensional forming







Diversified Packaging Protection Modes

Glue dispensing, coating, and potting. One device can achieve different types and levels of protection.



Thin Layer Spraying General Protection



Thick Layer Spraying High-grade Armor Protection



Fence+Filling Same UV Glue



Separate Fence Filled With Any Adhesive

ECO Highlights: Precise selective protection through spray printing, reducing glue waste. UV LED curing process, with no solvent evaporation, environmentally friendly.

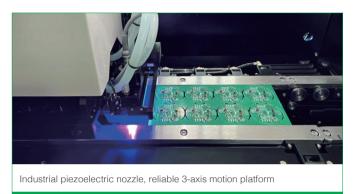
KP400



Whole region processing | Array printing nozzle | No masking process

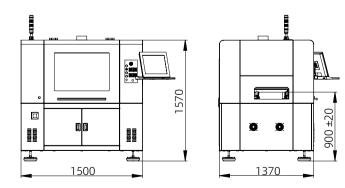
Equipment Introduction

KP400 applies 3D printing technology to electronic packaging protection, is a new concept of product packaging protection equipment. Accurately spray UV glue onto the areas that require protection, and form various 3D shapes through multi-layer stacking, providing high-strength protection for electronic components such as PCBA and FPC.





Precision CCD positioning system, dual head water-cooled UV-LED curing system



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Packaging Thickness & Speed	Technical Data	Remarks
Thickness of Single Layer	15/30/50 μm	Adjustable
Thickness of Multilayer	3 mm	Total Thickness
Fastest Speed for Single Layer Packaging	15 s	320*400 mm
Speed of Axes		
Number of Axes	3	
Movement Speed (XY)	200 or 300 or 400 mm/s	Low/Medium/High
Accuracy		
Packaging Accuracy	±0.1 mm	
Repeat Accuracy	±0.02 mm	
Work Space		
Max.panel size X- and Y-direction	400*320 mm	
Max Working Load	3 kg	
PCBA Characteristics		
Max. Size	400*320 mm	
Max. Component Height	≤10 mm (recommend)	
System Control		
Software System	KP400 Smart Software	Own IPR
Windows Operating System	Win10	
Power Supply		
Voltage	220V/ 50Hz/ 3kW	
Compressed Air	>0.5Mpa	
Ambient Temperature	17-28°C	
Relative Air Humidity	30-70%RH	
Machine Size		
Size (LWH)	1500*1370*1570 mm	
Weight	1250 kg	
Main Components		
Nozzle	Piezo printing nozzle	
Drive Motor (XY/ZR)	XY linear motor/ZR stepper motor	
Curing System	Dual head UV-LED(water cooled)	
Visual Positioning System	500W Industrial camera with high precision telecentric lens.	
UV Ink System	Independent dual loop	
Motion Guide Rail	Precision linear guide rail	
Track Data		
Max. height of conveying surface	25 mm above and 80 mm below	N
Opening & Closing Speed	30 mm/s	
Conveying Heigh	900±20 mm or 1000±20 mm	
Conveying Speed	5-10 m/min	
Conveyor Type:	High temperature and anti-static belt	
Transfer Direction	$L \rightarrow R \ (R \rightarrow L \text{ optional})$	
PCB Edge Space	≥5 mm	

Applicable Material Characteristics

Viscosity	10-15cps (Operation temperature 30°C~55°C)
Surface Tension	25-35dyn/cm
PH Value	6-8
Particle Size	D90≤200 nm
Curing Method	UV curing

* The material must pass KONIG test certification before used on the machine, otherwise it will cause damage to the glue system and print head.

